

PermiNex® 1000 & 2000

Low Temperature, Photoimageable Wafer Bonding Adhesives

PermiNex® 1000 and 2000 are negative tone, epoxy-based bonding resists for permanent and non-hermetic applications.

FEATURES

- Negative tone, photoimageable adhesives
- Alkaline and solvent developable series
- i-Line sensitivity, 3:1 aspect ratio imaging
- Low temperature processing at < 200°C
- High quality, void-free bonding
- Superb adhesion to silicon and glass
- Good process compatibility and high reliability

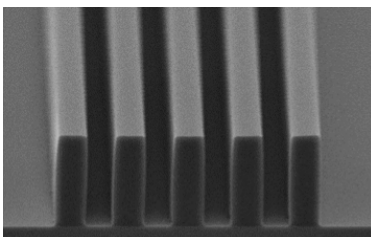
APPLICATIONS

- Definition and capping of cavity structures
- BAW and SAW devices
- Microfluidic devices

PRODUCT LINE

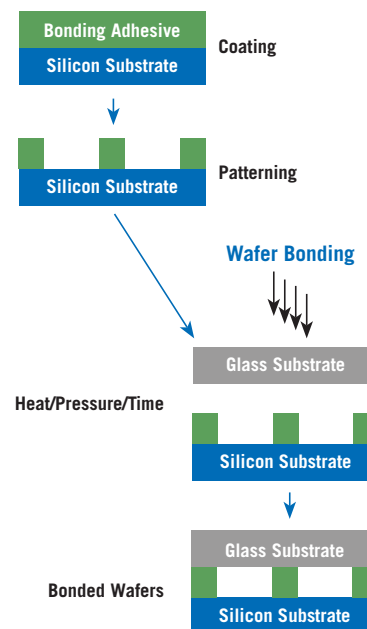
- PermiNex® 1000: solvent development with PN 1000 Developer
- PermiNex® 2000: aqueous development with 0.26N TMAH Developer

RESOLUTION CAPABILITY



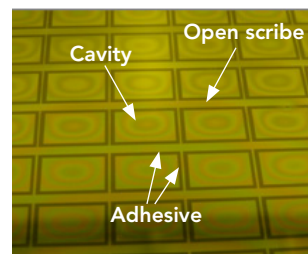
15 µm Thick PermiNex® 1000
5 µm Lines/Spaces

OVERALL PROCESS FLOW

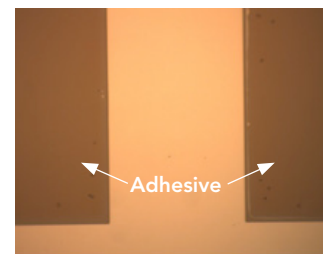


BONDING CAPABILITY

- High seal integrity after bonding
- High edge acuity
- No cracks or defects at corners
- Void-free conformal interface



Test cavity structures



Adhesive cavity wall